Special Issue

Advanced Image Analysis and Processing for Biomedical Applications

Message from the Guest Editors

This Special Issue aims to provide an assorted and complementary collection of contributions showing new advancements and applications of advanced imaging analysis and processing in the biomedical imaging area. The ultimate objective is to promote research and advancement in the field, by publishing high-quality research articles and reviews in this rapidly growing interdisciplinary field. Topics of interest include, but are not limited to, the following:

- Image enhancement, segmentation, registration, and fusion for biomedical applications;
- Image acquisition and processing for biomedical applications;
- Computer-aided diagnosis, surgery, therapy, treatment, and telemedicine systems;
- Application of machine learning and artificial intelligence in medicine;
- Mobile applications and low-cost systems;
- Deep learning for biomedical image analysis;
- Natural language processing for biomedical image analysis;
- Bio-inspired contour detection;
- Biomedical ultrasonics;
- Fluorescence image analysis;
- Super-resolution microscopy;
- Virtual surgery.

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About the Journal

Message from the Editor-in-Chief

As the world of science becomes ever more specialized, researchers may lose themselves in the deep forest of the ever increasing number of subfields being created. This open access journal Applied Sciences has been started to link these subfields, so researchers can cut through the forest and see the surrounding, or quite distant fields and subfields to help develop his/her own research even further with the aid of this multi-dimensional network.

Editor-in-Chief

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